Filename: PMP8286\_PRI\_REVC\_bom.xls Date: 08/27/2012

## PMP8286\_PRI\_REVC BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C1, C2	6.8uF	CAP ALUM 6.8UF 400V 20% RADIAL	0.315 inch	UCS2G6R8MPD	Nichicon
1	C3	2200pF	CAP CER 2200PF 250VAC X1Y2 RAD	7.00 Dia mm	STD	STD
1	C4	0.22uF	Capacitor, Ceramic, 50V, X7R, 15%	0603	STD	STD
1	D1	SMAJ120A	Diode, Transient Voltage Suppressor, 120V	SMA	SMAJ120A	Bourns
1	D2	RH06-T	Diode, Bridge, 0.5-A, 600-V	MiniDIP	RH06-T	Diodes
1	D3	MRA4007	Diode, Rectifier, 1A, 1000V, SMA	SMA	STD	STD
1	D5	BAS20	Diode, Swithcing, 200 mA, 200V	SOD-323	BAS20HT1	On Semi
1	F2	0.5A	FUSE SLOW 250VAC 500MA RADIAL	4x8.35 mm	RST500	BEL Fuse
1	L1	100uH	Inductor, 240mA	0.126 x 0.098 inch	ME3220-104MX	Coilcraft
1	Q1	AOD3N60	MOSFET N-CH 600V 2.5A DPAK		AOD3N60	Alpha & Omega Semiconductor Inc
1	R1	10k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R5	115k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R2	49.9	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R3	49.9	Resistor,1/4 watt, 5%	1206	STD	STD
1	R4	1	Resistor, Chip, 1/16W, 1%	0805	Std	Std
1	R6	3.01k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
2	R7, R9	10MEG	Resistor,1/4 watt, 5%	1206	STD	STD
1	R8	21.0k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	T2	550 uH	Transformer, Discontinuous Mode Flyback, ±7%	0.650x0.720 inch	RLTI-1061	Renco
2	TP1, TP2	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
1	U1	UCC28700DBV	IC, Constant Voltage, Constant Current PWM With Primary Side Regulation		UCC28700DBV	

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